Translation

PATENT COOPERATION TREATY



PCT

INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

(Chapter II of the Patent Cooperation Treaty)

(PCT Article 36 and Rule 70)

Applicantle and active Classic			
Applicant's or agent's file reference EL04009PCT	FOR FURTHER A	CTION	See Form PCT/IPEA/416
International application No. PCT/JP2004/004700		ate (day/month/year) 04 (31.03.2004)	Priority date (day/month/year) 03 April 2003 (03.04.2003)
International Patent Classification (IPC) or n H01L 29/78, 21/336, 21/318			03 April 2003 (03.04.2003)
Applicant	ОНМІ,	Tadahiro	
This report is the international prelin Authority under Article 35 and trans	ninary examination rep mitted to the applicant	port, established by this according to Article 36	International Preliminary Examining 5.
2. This REPORT consists of a total of			heet.
This report is also accompanied by A	NNEXES, comprising	g:	
a. (sent to the applicant and	to the International Bi	ureau) a total of	sheets, as follows:
sheets of the descr and/or sheets cont Administrative Ins	aining rectifications at	frawings which have be athorized by this Autho	een amended and are the basis of this report rity (see Rule 70.16 and Section 607 of the
sheets which supe beyond the disclos Supplemental Box	sure in the internations	ut which this Authority al application as filed, a	considers contain an amendment that goes as indicated in item 4 of Box No. I and the
	, conta dicated in the Suppler	ining a sequence listing	be and number of electronic carrier(s)) g and/or tables related thereto, in computer Sequence Listing (see Section 802 of the
4. This report contains indications relati	ing to the following ite	ems:	
Box No. I Basis of the rep	oort		
Box No. II Priority			
1 7		gard to novelty, inventi	ve step and industrial applicability
		2) with record to navel	ty, inventive step or industrial applicability;
citations and ex	pianations supporting	such statement	iy, inventive step or industrial applicability;
 7	in the international ap	•	
Box No. VIII Certain observa	tions on the internation	nal application	
Date of submission of the demand		Date of completion of	this report
15 August 2004 (15.08.2	2004)	18 Feb	oruary 2005 (18.02.2005)
Name and mailing address of the IPEA/JP		Authorized officer	
Facsimile No.		Telephone No.	

International application No.

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Box No. 1	[Basis of the report
		to the language, this report is based on the international application in the language in which it was filed, unless adicated under this item.
		report is based on translations from the original language into the following language, the is language of a translation furnished for the purpose of:
Ţ		international search (under Rules 12.3 and 23.1(b))
		publication of the international application (under Rule 12.4)
		international preliminary examination (under Rules 55.2 and/or 55.3)
furnish and ar	hed to re not	d to the elements of the international application, this report is based on (replacement sheets which have been to the receiving Office in response to an invitation under Article 14 are referred to in this report as "originally filed" annexed to this report):
	The i	nternational application as originally filed/furnished
		escription:
1	pages	
	pages	
l	page	
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	a seq	quence listing and/or any related table(s) - see Supplemental Box Relating to Sequence Listing.
}		
3.	The	amendments have resulted in the cancellation of:
1		the description, pages
}	T	the claims, Nos.
}	Ħ	the drawings, sheets/figs
}	Ħ	the sequence listing (specify):
1	H	any table(s) related to sequence listing (specify):
ļ	لــا	
	made	report has been established as if (some of) the amendments annexed to this report and listed below had not been e, since they have been considered to go beyond the disclosure as filed, as indicated in the Supplemental Box e 70.2(c)).
	\sqcup	the description, pages
ł		the claims, Nos.
{		the drawings, sheets/figs
1		the sequence listing (specify):
ļ		any table(s) related to sequence listing (specify):
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* If iten	n 4 aj	oplies, some or all of those sheets may be marked "superseded."

International application No.

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. Statement			
Novelty (N)	Claims	2, 4-6, 8-10, 12, 14-16, 18-20	YES
	Claims	1, 3, 7, 11, 13, 17	NO
Inventive step (IS)	Claims	10, 20	YES
	Claims	1-9, 11-19	NO
Industrial applicability (IA)	Claims	1-20	YES
	Claims		NO

2. Citations and explanations (Rule 70.7)

Document 1: JP, 2002-343790, A (NEC Corp.), 29 November, 2002 (29.11.02), full text

Document 2: JP, 2003-17687, A (Hitachi, Ltd.), 17 January, 2003 (17.01.03), full text

Document 3: JP, 2001-332547, A (Toshiba Corp.), 30 November, 2001 (30.11.01), full text

Document 4: JP, 2003-8004, A (Fujitsu Ltd.), 10 January, 2003 (10.01.03), full text

Document 5: JP, 2000-4018, A (Texas Instruments Inc.), 7 January, 2000 (07.01.00), full text

Claim 1

The subject matter of claim 1 is described in document 1 (paragraphs [0019]-[0062]), document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), and document 3 (paragraph [0038]-[0109]), and so does not appear to be novel or to involve an inventive step.

2. Claim 2

The subject matter of claim 2 does not appear to involve an inventive step for the following reasons A and B.

- A. Document 1 (paragraph [0005]) describes that the ALD method is used for depositing gate insulation film because it allows a film of extremely good uniformity to be created in the faces of a silicon wafer compared with the CVD method. Plasma CVD technology is well known and commonly used as a technology of depositing insulation film by means of the CVD method. Accordingly, there would be no particular technical difficulty involved in using plasma CVD technology for depositing gate insulation film in the invention described in document 1 (paragraphs [0019]-[0062]).
- B. Plasma CVD technology is well known and commonly used as a technology of depositing insulating film by means of the CVD method. A person skilled in the art could have normally deposited gate insulation film by means of plasma CVD technology in the invention described in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), and the invention described in document 3 ([0038]-[0109]).

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Supplemental Box

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3. Claim 3

The subject matter of claim 3 does not appear to be novel or to involve an inventive step for the following reasons A and B.

- A. The subject matter of claim 3 is described in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]).
- B. A person skilled in the art could have easily considered a constitution wherein silicon nitride film is provided between a silicon substrate and gate insulation film is proposed in the inventions described in document 1 (paragraphs [0019]-[0062]) and the invention in document 3 ([0038]-[0109]), based on e.g., the well-known technologies shown in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), documents 4 and 5.

4. Claims 4-6

The subject matters of claims 4-6 do not appear to involve an inventive step for the following reasons.

A person skilled in the art could have easily conceived a constitution wherein silicon nitride film is proposed on insulation film in the inventions described in document 1 (paragraphs [0019]-[0062]), the invention described in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), and the invention described in document 3 ([0038]-[0109]) wherein silicon nitride film is provided on gate insulation film, for example, based on the well-known technologies shown in documents 4 and 5.

A person skilled in the art could have normally used the direct nitrification technology using plasma, which is a well-known and commonly used nitrification process, in forming silicon nitride film between a silicon substrate and gate insulation film.

Whether a laminate structure of silicon nitride film and gate insulation film is repeated into a multilaminate structure would be a matter that a person skilled in the art could choose freely as required.

5. Claim 7

Document 1 (paragraph [0019]-[0062]) describes that gate insulation film is formed with its composition varying continuously, and document 3 ([0038]-[0109]) describes that gate insulation film is so constituted that the concentration of its component metal gradually decreases from its interface with the gate electrode to its interface with the silicon substrate. Accordingly, the subject matter of claim 7 does not appear to be novel or to involve an inventive step.

6. Claims 8 and 9

The subject matters of claims 8 and 9 do not appear to involve an inventive step for the following reasons.

A person skilled in the art could have easily conceived a constitution wherein insulation film made of single-crystal alumina is provided between a silicon substrate and a gete insulation film in the inventions described in document 1 (paragraphs [0019]-[0062]), the invention described in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), and the invention described in document 3 ([0038]-[0109]), for example, based on the well-known technologies shown in documents 4 and 5.

In addition a person skilled in the art could have normally used plasma CVD technology, which is a well-known technology of depositing insulating film, to form the insulation film made of single-crystal alumina.

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Claim 10

The subject matter of claim 10 is neither described in any of the documents cited in the ISR nor obvious to a person skilled in the art.

8. Claim 11

The subject matter of claim 11 is described in document 1 (paragraphs [0019]-[0062]), document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), and document 3 ([0038]-[0109]), and so does not appear to be novel or to involve an inventive step.

9. Claim 12

The subject matter of claim 12 does not appear to involve an inventive step for the following reasons A and B.

- A. Document 1 (paragraph [0005]) describes that the ALD method is used for depositing gate insulation film because it allows a film of extremely good uniformity to be created in the faces of a silicon wafer compared with the CVD method. Plasma CVD technology is well known and commonly used as a technology of depositing insulation film by means of the CVD method. Accordingly, there would be no particular technical difficulty involved in using plasma CVD technology for depositing gate insulation film in the invention described in document 1 (paragraphs [0019]-[0062]).
- B. Plasma CVD technology is well known and commonly used as a technology of depositing insulating film by means of the CVD method. A person skilled in the art could have normally deposited gate insulation film by means of plasma CVD technology in the invention described in document 2 (claims 4-8 and paragraphs [0048]-[0054]) and the invention described in document 3 ([0038]-[0109]).

10. Claim 13

The subject matter of claim 13 does not appear to be novel or to involve an inventive step for the following reasons A and B.

- A. The subject matter of claim 13 is described in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]).
- B. A person skilled in the art could have easily conceived a constitution wherein silicon nitride film is provided between a silicon substrate and gate insulation film in the inventions described in document 1 (paragraphs [0019]-[0062]) and the invention described in document 3 ([0038]-[0109]), for example, based on the well-known technologies shown in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), documents 4 and 5.

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11. Claims 14-16

The subject matters of claims 14-16 do not appear to involve an inventive step for the following reasons.

A person skilled in the art could have easily conceived a constitution wherein silicon nitride film is provided on gate insulation film in the inventions described in document 1 (paragraphs [0019]-[0062]), the invention described in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), and the invention described in document 3 ([0038]-[0109]), for example, based on the well-known technologies shown in documents 4 and 5.

A person skilled in the art could have normally used the direct nitrification technology using plasma, which is a well-known and commonly used nitrification process, in forming silicon nitride film between a silicon substrate and gate insulation film.

Whether a laminate structure of silicon nitride film and gate insulation film is repeated into a multilaminate structure would be a matter that a person skilled in the art could choose freely as required.

12. Claim 17

Document 1 (paragraph [0019]-[0062]) describes that gate insulation film is formed with its composition varying continuously, and document 3 ([0038]-[0109]) describes that gate insulation film is so constituted that the concentration of its component metal gradually decreases from its interface with the gate electrode to its interface with the silicon substrate. Accordingly, the subject matter of claim 17 does not appear to be novel or to involve an inventive step.

13. Claims 18 and 19

The subject matters of claims 18 and 19 do not appear to involve an inventive step for the following reasons.

A person skilled in the art could have easily conceived a constitution wherein insulation film made of single-crystal alumina is provided between a silicon substrate and gate insulation film the inventions described in document 1 (paragraphs [0019]-[0062]), the invention described in document 2 (claims 4-8 and 12, and paragraphs [0048]-[0054]), and the invention described in document 3 ([0038]-[0109]), for example, based on the well-known technologies shown in documents 4 and 5.

In addition, a person skilled in the art could have normally used plasma CVD technology, which is a well-known technology of depositing insulating film, to form the insulation film made of single-crystal alumina.

14. Claim 20

The subject matter of claim 20 is neither described in any of the documents cited in the ISR nor obvious to a person skilled in the art.